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### Three-state memory device

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#### Abstract

The present disclosure relates to an integrated chip including a bottom electrode arranged within a dielectric layer. A memory element is directly over the bottom electrode and is arranged within the dielectric layer. A top electrode is directly over the memory element and is arranged within the dielectric layer. A conductive via is directly over the top electrode. A pair of lines that extend along opposing sidewalls of the top electrode are directly over, and intersect, an uppermost surface of the memory element. The pair of lines are directly under, and intersect, a lowermost surface of the via.

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## Background/Summary

REFERENCE TO RELATED APPLICATION (1) This Application is a Divisional of U.S. application Ser. No. 17/412,509, filed on Aug. 26, 2021, the contents of which are hereby incorporated by reference in their entirety.

### BACKGROUND

(1) Many modern day electronic devices contain electronic memory. Electronic memory may be volatile memory or non-volatile memory. Non-volatile memory is able to store data in the absence of power, whereas volatile memory is not. Some examples of next generation electronic memory include magnetoresistive random-access memory (MRAM), resistive random-access memory (RRAM), phase-change random-access memory (PCRAM), and conductive-bridging random-access memory (CBRAM).

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# Description

## BRIEF DESCRIPTION OF THE DRAWINGS

- (1) Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.
- (2) FIG. 1 illustrates a cross-sectional view of some embodiments of a memory device comprising a top electrode over a memory element, the top electrode configured to create an open circuit in the memory device.
- (3) FIG. 2 illustrates a cross-sectional view of some embodiments of the memory device of FIG. 1 in which the memory element comprises multiple layers.
- (4) FIG. 3 illustrates a top view of some embodiments of the memory device of FIGS. 1 and 2.
- (5) FIG. 4 illustrates a three-dimensional view of some embodiments of the memory device of FIG. 1.
- (6) FIG. 5 illustrates a cross-sectional view of some embodiments of the memory device of FIG. 1 in which the top electrode extends through a hard mask to an uppermost surface of the memory element.
- (7) FIG. 6 illustrates a cross-sectional view of some embodiments of the memory device of FIG. 1 in which a dielectric structure is on an uppermost surface of the memory element.
- (8) FIG. 7 illustrates a cross-sectional view of some embodiments of an integrated chip comprising the memory device of FIG. 1 arranged over a substrate.
- (9) FIG. 8 illustrates a three-dimensional view of some embodiments of a memory array comprising a plurality of memory cells.
- (10) FIGS. 9-21 illustrate cross-sectional views of some embodiments of a method for forming a memory device comprising a top electrode over a memory element and a source line coupled to the top electrode.
- (11) FIG. 22 illustrates a flow diagram of some embodiments of a method for forming a memory device comprising a top electrode over a memory element and a source line coupled to the top electrode.

## DETAILED DESCRIPTION

(12) The following disclosure provides many different embodiments, or examples, for implementing different features of the provided subject matter. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

(13) Further, spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper” and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

(14) Many integrated chips include memory devices. A memory device may include a plurality of memory elements arranged in an array comprising a number of rows and columns. For example, a memory element may include a magnetic tunnel junction (MTJ) or the like.

(15) In some instances, one or more memory elements in a memory device may fail over time. As a result, the row and/or column in which the failed element resides may be discarded. This may result in all of the memory elements in the respective row and/or column going unused, even if those elements have not failed. Thus, a plurality of working memory elements may be wasted in this process.

(16) To mitigate this issue, some memory elements are configured to have three different operating states. For example, a memory element may be configured to have a low resistance state (e.g., a logic “1”), a high resistance state (e.g., a logic “0”), and a short circuit state (e.g., a very low resistance state). In some instances, the memory device may be able to disregard memory elements exhibiting the short circuit state without discarding the other elements in the row and/or column. In other words, working memory elements in a row and/or column that contains a failed element may not have to be wasted. Thus, memory element waste may be minimized and memory density may be increased.

(17) However, a challenge with these memory devices is that the short circuit state may have highly variable resistance. For example, different memory elements in the short circuit state may have a number of different low resistances. Further, in some instances, the short circuit state may result in a resistance that is similar to the low resistance state (e.g., the logic “1” state). This high variability may make it difficult for the memory device to identify which state each memory element is in. Thus, a performance and/or a reliability of the memory device may be low.

(18) Various embodiments of the present disclosure are related to a memory device comprising a breakable top electrode over a memory element for improving a performance of the memory device. The memory device comprises a memory element directly over a bottom electrode. A top electrode is directly over the memory element. A width of the top electrode is less than a width of the memory element. A conductive via is directly over the top electrode. A first conductive line is directly over the conductive via. A source line is adjacent to the first conductive line. The source line is electrically coupled to the top electrode through the first conductive line and the conductive via.

(19) The memory device may read and write the memory element by providing a read signal and a write signal, respectively, to the memory element. In some instances, if the memory device detects that the memory element has failed, the source line is configured to provide a breakdown signal to the top electrode. The breakdown signal has a voltage that is higher than a voltage of the read signal and/or a voltage of the write signal. Further, the voltage of the breakdown signal is high enough to cause the top electrode to break (e.g., by way of electromigration) and create an open circuit. By creating an open circuit in series with the failed memory element (i.e., by creating an open circuit state), the memory device may be able to disregard the failed memory element without discarding any other elements in a same row and/or column as the failed memory element. Further, the open circuit state may have little or no variability (e.g., relative to a short circuit state). Furthermore, the open circuit state may exhibit a very large resistance (e.g., much higher than that of a logic “0” high resistance state), thereby reducing a difficulty for the memory device to identify which state each memory element is exhibiting. Thus, a performance and/or a reliability of the memory device may be improved.

(20) FIG. 1 illustrates a cross-sectional view **100** of some embodiments of a memory device comprising a top electrode **116** over a memory element **110**, the top electrode **116** configured to create an open circuit in the memory device. In some embodiments, the cross-sectional view **100** of FIG. 1 may, for example, be taken across line A-A' of FIG. 3. In some embodiments, FIG. 1 is illustrated in a z-y plane (see, for example, z-axis **101z** and y-axis **101y**).

(21) The memory device comprises a bottom electrode **102** arranged within a dielectric structure

**103.** The memory element **110** is arranged within the dielectric structure **103** and is directly over the bottom electrode **102**. In some embodiments, the memory element **110** may, for example, be or comprise a magnetoresistive memory element (e.g., a magnetic tunnel junction (MTJ) or the like), a phase-change memory element, a resistive memory element, or some other suitable type of memory element. In some embodiments, a hard mask **112** is arranged within the dielectric structure **103** and is directly over the memory element **110**.

(22) The top electrode **116** is arranged within the dielectric structure **103** and is directly over the hard mask **112**. In some embodiments, a lowermost surface **116a** of the top electrode **116** is on an uppermost **112a** surface of the hard mask **112**. In some embodiments, the dielectric structure **103** laterally surrounds the top electrode **116**, and the dielectric structure **103** is on the uppermost surface **112a** of the hard mask **112**.

(23) A width of the top electrode **116** is less than a width of the memory element **110**. For example, in some embodiments, a pair of vertical lines **130** that extend along opposing sidewalls **116s** of the top electrode **116** are directly over, and intersect, an uppermost surface **110a** of the memory element **110**. In some embodiments, the pair of vertical lines **130** are also directly under, and intersect, a lowermost surface **120a** of the conductive via **120**. In some embodiments, the pair of vertical lines **130** are also directly over, and intersect, the uppermost surface **112a** of the hard mask **112**. In some embodiments, a ratio of the width of the top electrode **116** to the width of the memory element **110** is less than 1, is less than 0.5, is about 0.1 to 0.5, or is some other suitable value.

(24) A conductive via **120** is arranged within the dielectric structure **103** and is directly over the top electrode **116**. A first conductive line **122** is arranged within the dielectric structure **103** and is directly over the conductive via **120**. The first conductive line **122** is disposed at a first height **126** over the memory element **110**.

(25) A source line **124** is arranged within the dielectric structure **103** and is adjacent to the first conductive line **122**. In some embodiments, the source line **124** is also disposed at the first height **126**. In some embodiments, the source line **124** is arranged on a sidewall **122s** of the first conductive line **122**. The source line **124** is electrically coupled to the top electrode **116** through the first conductive line **122** and the conductive via **120**.

(26) The source line **124** is configured (e.g., if the memory device detects that the memory element **110** has failed) to provide a breakdown signal to the top electrode **116**. A voltage of the breakdown signal is higher than a voltage of a read signal for reading the memory element **110**, and is higher than a voltage of a write signal for writing to the memory element **110**. Further, the voltage of the breakdown signal is high enough (e.g., greater than about 3 volts or some other suitable value) to cause the top electrode **116** to break (e.g., experience electromigration), thereby creating an open circuit in the path between the bottom electrode **102** and the conductive via **120**. In some embodiments, as a result of the electromigration, a void (e.g., as illustrated by dashed region **128**) may exist somewhere along the top electrode **116**, and the void may separate the top electrode **116** from the conductive via **120** and/or from another portion of the top electrode **116** (i.e., the void may exist at the open circuit and/or may establish the open circuit).

(27) By creating an open circuit in series with the memory element **110**, the memory device may be able to disregard the memory element **110** without discarding any other memory elements (not shown) in a same row and/or column as the memory element **110**. Further, the open circuit state may have little or no variability (e.g., relative to a short circuit state). Furthermore, the open circuit state may exhibit a very large resistance (e.g., much higher than that of a logic “0” high resistance state), thereby reducing a difficulty for the memory device to identify which state each memory element is exhibiting. Thus, a performance and/or a reliability of the memory device may be improved.

(28) Further, because the top electrode **116** has a small width (e.g., because the ratio of the width of the top electrode **116** to the width of the memory element **110** is less than 1, is less than 0.5, is about 0.1 to 0.5, or some other suitable value), the voltage across the top electrode **116** that is

provided by the source line **124** may more easily break the top electrode **116**. In other words, the source line **124** may need to provide a lower voltage to break the top electrode **116** than would otherwise be necessary if the top electrode **116** had a larger width. Thus, a performance of the memory device may be further improved.

(29) In some embodiments, the void (e.g., **128**) may exist at an interface between the top electrode **116** and the conductive via **120**. In some embodiments, the void may be or comprise one or more air gaps. For example, in some embodiments, the void may comprise air, a combination of air and some metal residue, or the like.

(30) FIG. **2** illustrates a cross-sectional view **200** of some embodiments of the memory device of FIG. **1** in which the memory element **110** comprises multiple layers. In some embodiments, the cross-sectional view **200** of FIG. **1** may, for example, be taken across line B-B' of FIG. **3**. In some embodiments, FIG. **2** is illustrated in a z-x plane (see, for example, z-axis **101z** and x-axis **101x**).

(31) In some embodiments, the memory element **110** comprises a magnetic reference layer **104**, a tunnel barrier layer **106** directly over the magnetic reference layer **104**, and a magnetic free layer **108** directly over the tunnel barrier layer **106**. In some embodiments, the hard mask **112** vertically separates a lowermost surface **116a** of the top electrode **116** from an uppermost surface **110a** of the memory element **110**.

(32) In some embodiments, the top electrode **116** may have a curved lowermost surface (e.g., as illustrated by dashed line **132**). In such embodiments, the curved lowermost surface of the top electrode **116** is below an uppermost surface **112a** of the hard mask **112**. In other words, in such embodiments, the curved lowermost surface of the top electrode **116** extends into a top of the hard mask **112**. Further, in such embodiments, the hard mask **112** has a curved upper surface that abuts the curved lowermost surface of the top electrode **116**.

(33) In some embodiments, one or more sidewalls of the top electrode **116** are tapered (e.g., as illustrated by a dashed lines **134**). In other words, in such embodiments, an angle between the one or more sidewalls of the top electrode **116** and a lowermost surface **116a** of the top electrode **116** is greater than 90 degrees. In yet other words, in such embodiments, a width of the top electrode **116** may increase along the height of the top electrode **116**.

(34) FIG. **3** illustrates a top view **300** of some embodiments of the memory device of FIGS. **1** and **2**. In some embodiments, FIG. **3** is illustrated in a y-x plane (see, for example, y-axis **101y** and x-axis **101x**).

(35) In some embodiments, a first perimeter **316** of a lowermost surface of the top electrode (not shown) is arranged within a second perimeter **310** of an uppermost surface of the memory element (not shown). Further, in some embodiments, the first perimeter **316** is also arranged within a third perimeter **320** of a lowermost surface of the conductive via (not shown).

(36) In some embodiments, the first conductive line **122** is elongated in a first direction (e.g., along the x-axis **101x**) while the source line **124** is elongated in a second direction (e.g., along the y-axis **101y**) transverse to the first direction.

(37) FIG. **4** illustrates a three-dimensional view **400** of some embodiments of the memory device of FIG. **1**.

(38) In some embodiments, the bottom electrode **102**, the memory element **110**, the hard mask **112**, and the top electrode **116** may be shaped like rectangular prisms, as illustrated in FIG. **4**. However, it will be appreciated that in some alternative embodiments, the bottom electrode **102**, the memory element **110**, the hard mask **112**, and the top electrode **116** may alternatively have cylindrical shapes.

(39) In some embodiments, the bottom electrode **102** may, for example, comprise titanium nitride, tantalum nitride, tungsten, copper, or some other suitable conductive material. In some embodiments, a width of the bottom electrode **102** (e.g., along the y-axis **101y**) may, for example, be about 20 nanometers to 50 nanometers or some other suitable value. In some embodiments, a thickness of the bottom electrode **102** (e.g., along the z-axis **101z**) may, for example, be about 20

nanometers to about 100 nanometers or some other suitable value.

(40) In some embodiments, a width of the memory element **110** may, for example, be about 20 nanometers to 50 nanometers or some other suitable value. In some embodiments, a thickness of the memory element **110** may, for example, be about 10 nanometers to 30 nanometers or some other suitable value.

(41) In some embodiments, the magnetic reference layer **104** and/or the magnetic free layer **108** may, for example, comprise a cobalt-iron-boron alloy, or some other suitable material. In some embodiments, the tunnel barrier layer **106** may, for example, comprise magnesium oxide, aluminum oxide, or some other suitable material.

(42) In some embodiments, the hard mask **112** may, for example, comprise titanium nitride or some other suitable conductive material. In some embodiments, a width of the hard mask **112** may, for example, be about 20 nanometers to 50 nanometers or some other suitable value. In some embodiments, a thickness of the hard mask **112** may, for example, be about 50 nanometers to 150 nanometers or some other suitable value.

(43) In some embodiments, the top electrode **116** may, for example, comprise copper, a copper-aluminum alloy, or some other suitable material. In some embodiments, a width of the top electrode **116** may, for example, be about 5 nanometers to 10 nanometers or some other suitable value. In some embodiments, a thickness of the top electrode **116** may, for example, be about 10 nanometers to 50 nanometers or some other suitable value.

(44) In some embodiments, the conductive via **120**, the first conductive line **122**, and/or the source line **124** may, for example, comprise titanium nitride, tantalum nitride, tungsten, copper, or some other suitable conductive material. In some embodiments, a width of the conductive via **120** may, for example, be about 10 nanometers to 40 nanometers or some other suitable value. In some embodiments, a thickness of the conductive via **120** may, for example, be about 10 nanometers to about 50 nanometers or some other suitable value.

(45) In some embodiments, the dielectric structure (e.g., **103** of FIG. **3**) may, for example, comprise one or more dielectric layers (see, for example, first dielectric layer **114** and/or second dielectric layer **118** of FIG. **21**). In some embodiments, the one or more dielectric layers may, for example, comprise silicon dioxide, silicon nitride, silicon carbide, silicon oxycarbide, silicon oxynitride, or some other suitable material.

(46) It should be noted that the dielectric structure (**103** of FIG. **3**) is not shown in FIG. **4** for simplicity and clarity of illustration.

(47) FIG. **5** illustrates a cross-sectional view **500** of some embodiments of the memory device of FIG. **1** in which the top electrode **116** extends through a hard mask **112** to an uppermost surface **110a** of the memory element **110**.

(48) In such embodiments, sidewalls of the top electrode **116** are on sidewalls of the hard mask. In some embodiments, the top electrode **116** is in direct contact with the memory element **110** (e.g., with the magnetic free layer **108**). In some embodiments, a lowermost surface **116a** of the top electrode **116** is on an uppermost surface **110a** of the memory element **110** (e.g., on an uppermost surface of the magnetic free layer).

(49) In some other embodiments, the top electrode **116** may have a curved lowermost surface (e.g., as illustrated by dashed line **136**). In such embodiments, the curved lowermost surface of the top electrode **116** is below the uppermost surface **110a** of the memory element **110** (e.g., below an uppermost surface of the magnetic free layer **108**). In other words, in such embodiments, the curved lowermost surface of the top electrode **116** extends into a top of the memory element **110** (e.g., into a top of the magnetic free layer **108**). Further, in such embodiments, the memory element **110** (e.g., the magnetic free layer **108**) has a curved upper surface that abuts the curved lowermost surface of the top electrode **116**.

(50) FIG. **6** illustrates a cross-sectional view **600** of some embodiments of the memory device of FIG. **1** in which a dielectric structure **103** is on an uppermost surface **110a** of the memory element

**110.**

(51) In such embodiments, the memory device is devoid of the hard mask (e.g., **112** of FIG. **1**). In some embodiments, the dielectric structure **103** is in direct contact with the uppermost surface **110a** of the memory element **110**.

(52) In some embodiments, a lowermost surface **116a** of the top electrode **116** is on an uppermost surface **110a** of the memory element (e.g., on an uppermost surface of the magnetic free layer **108**). In some other embodiments, the top electrode **116** may have a curved lowermost surface (e.g., as illustrated by dashed line **138**) that extends below the uppermost surface **110a** of the memory element **110** (e.g., below the uppermost surface of the magnetic free layer **108**).

(53) FIG. **7** illustrates a cross-sectional view **700** of some embodiments of an integrated chip comprising the memory device of FIG. **1** arranged over a substrate **702**.

(54) In some embodiments, a semiconductor device **704** is arranged along the substrate **702**, one or more dielectric layers **706** are over the substrate **702**, one or more conductive interconnects **708** (e.g., contacts, vias, wires, or the like) are within the one or more dielectric layers **706**, and a landing pad **710** is over the one or more conductive interconnects **708**. In some embodiments, the bottom electrode **102** may be in direct contact with the landing pad **710**. In some embodiments, the memory element **110** may be electrically coupled to the semiconductor device **704** through the bottom electrode **102**, the landing pad **710**, and the one or more conductive interconnects **708**.

(55) FIG. **8** illustrates a three-dimensional view **800** of some embodiments of a memory array comprising a plurality of memory cells **804a-d**.

(56) In some embodiments, a first word line **802a** and a second word line **802b** extend along a first axis (e.g., y-axis **101y**). The second word line **802b** is adjacent to the first word line **802a** and is spaced apart from the first word line **802a**. In some embodiments, a first memory cell **804a** and a second memory cell **804b** are directly over the first word line **802a**, while a third memory cell **804c** and a fourth memory cell **804d** are directly over the second word line **802b**.

(57) In some embodiments, the first memory cell **804a**, the second memory cell **804b**, the third memory cell **804c**, and the fourth memory cell **804d** each comprise a bottom electrode **102**, a memory element **110** directly over the bottom electrode **102**, a hard mask **112** directly over the memory element **110**, and a top electrode **116** directly over the hard mask **112**. In some embodiments, each of the memory cells (e.g., **804a-d**) further comprise a selector **806**.

(58) Although FIG. **8** does not show features overlying the top electrodes **116**, it will be appreciated that in some embodiments, the top electrodes **116** are electrically coupled to overlying conductive features (not shown). For example, in such embodiments, the overlying conductive features may include one or more first conductive lines (e.g., **122** of FIG. **1**) and one or more source lines (e.g., **124** of FIG. **1**) coupled to the one or more first conductive lines, as illustrated, for example, in FIG. **1**. Further, although FIG. **8** illustrates a four cell memory array, it will be appreciated that in some other embodiments, arrays of other sizes are also feasible.

(59) FIGS. **9-21** illustrate cross-sectional views **900-2100** of some embodiments of a method for forming a memory device comprising a top electrode **116** over a memory element **110** and a source line **124** coupled to the top electrode **116**. Although FIGS. **9-21** are described in relation to a method, it will be appreciated that the structures disclosed in FIGS. **9-21** are not limited to such a method, but instead may stand alone as structures independent of the method.

(60) As shown in cross-sectional view **900** of FIG. **9**, a first magnetic layer **904** is formed directly over a first conductive layer **902**, an insulator layer **906** is formed directly over the first magnetic layer **904**, and a second magnetic layer **908** is formed directly over the insulator layer **906**.

(61) In some embodiments, the first conductive layer **902** may, for example, comprise titanium nitride, tantalum nitride, tungsten, copper, or some other suitable material. In some embodiments, the first magnetic layer **904** and/or the second magnetic layer **908** may, for example, be formed by depositing a cobalt-iron-boron alloy or some other suitable material by a sputtering process or some other suitable process. In some embodiments, the insulator layer **906** may, for example, be formed



by depositing magnesium oxide, aluminum oxide, or some other suitable material by a chemical vapor deposition (CVD) process, a physical vapor deposition (PVD) process, an atomic layer deposition (ALD) process, or some other suitable process.

(62) As shown in cross-sectional view **1000** of FIG. **10**, a hard mask **112** is formed directly over the second magnetic layer (e.g., **908** of FIG. **9**). The second magnetic layer (e.g., **908** of FIG. **9**), the insulator layer (e.g., **906** of FIG. **9**), the first magnetic layer (e.g., **904** of FIG. **9**), and the first conductive layer (e.g., **902** of FIG. **9**) are then etched according to the hard mask **112** to form a bottom electrode **102** from the first conductive layer and to form a memory element **110** from the first magnetic layer, the insulator layer, and the second magnetic layer. For example, the etching forms a magnetic reference layer **104** from the first magnetic layer, a tunnel barrier layer **106** from the insulator layer, and a magnetic free layer **108** from the second magnetic layer.

(63) In some embodiments, the etching may, for example, comprise a dry etching process (e.g., a reactive ion etching process, an ion beam etching process, or the like) or some other suitable etching process.

(64) In some embodiments, the hard mask **112** may, for example, be formed by depositing titanium nitride or some other suitable hard mask material by a CVD process, a PVD process, an ALD process, a sputtering process, or some other suitable process, and by patterning the hard mask material by a photolithography process or some other suitable process. In some embodiments, the hard mask **112** is removed from over the memory element **110** after the etching (see, for example, FIG. **6**).

(65) Although FIGS. **9** and **10** illustrate forming an MTJ, it will be appreciated that in some alternative embodiments, some other type of memory element may alternatively be formed over the bottom electrode **102**. For example, in some alternative embodiments, one or more data storage layers may be formed over a first conductive layer and may be patterned to form a memory element.

(66) As shown in cross-sectional view **1100** of FIG. **11**, a first dielectric layer **114** is formed directly over the hard mask **112** and surrounding the memory element **110**. In some embodiments, the first dielectric layer **114** may, for example, be formed by depositing silicon dioxide, silicon nitride, silicon carbide, silicon oxycarbide, silicon oxynitride, or some other suitable material by a CVD process, a PVD process, an ALD process, or some other suitable process.

(67) As shown in cross-sectional view **1200** of FIG. **12**, a first masking layer **1202** is formed directly over the first dielectric layer **114**. The first dielectric layer **114** is then etched according to the first masking layer **1202** to form a first opening **1204** in the first dielectric layer **114**. In some embodiments, the first opening **1204** is directly over the hard mask **112** and uncovers an upper surface of the hard mask **112**.

(68) In some embodiments, the first masking layer **1202** may, for example, be or comprise a photoresist mask, a hard mask, or the like. In some embodiments, the etching may, for example, comprise a dry etching process or some other suitable process. In some embodiments, the first masking layer **1202** is removed after the etching.

(69) In some embodiments, the etch, and thus the first opening **1204**, may extend into the hard mask **112** (see, for example, **132** of FIG. **2**). In some other embodiments, the etch may extend through the hard mask **112** to an uppermost surface of the memory element **110** (see, for example, FIG. **5**). In yet other embodiments, the etch may extend through the hard mask **112** and into an uppermost surface of the memory element **110** (see, for example, **136** of FIGS. **5** and/or **138** of FIG. **6**).

(70) In some embodiments, a profile of the etch may be angled such that angles between sidewalls of the first dielectric layer **114** that define the first opening **1204** and an upper surface of the hard mask **112** are greater than 90 degrees (see, for example, **134** of FIG. **2**).

(71) The sidewalls of the first dielectric layer **114** that define the first opening **1204** are laterally set back from the sidewalls of the memory element **110**. A distance between the sidewalls of the first

dielectric layer **114** that define the first opening **1204** (i.e., a width of the first opening **1204**) is less than a distance between the sidewalls of the memory element **110** (i.e., is less than the width of the memory element **110**). In some embodiments, a ratio of the width of the first opening **1204** (e.g. along y-axis **101y**) to a width of the memory element **110** is less than 0.5, is about 0.1 to 0.5, or is some other suitable value.

(72) As shown in cross-sectional view **1300** of FIG. **13**, a second conductive layer **1302** is formed over the first dielectric layer **114**, directly over the hard mask **112**, and in the first opening **1204** to form a top electrode **116** directly over the hard mask **112** and in the first opening **1204**. In some embodiments, the second conductive layer **1302** may, for example, be formed by depositing copper, some copper-aluminum alloy, or some other suitable material by a sputtering process, an electrochemical deposition process, an electroless deposition process, or some other suitable process.

(73) As shown in cross-sectional view **1400** of FIG. **14**, a planarization process is performed on the second conductive layer **1302** to remove the second conductive layer **1302** from over the first dielectric layer **114** and to further define the top electrode **116**. In some embodiments, the planarization process is also performed on the first dielectric layer **114**. In some embodiments, an uppermost surface of the top electrode **116** and uppermost surfaces of the first dielectric layer **114** are coplanar after the planarization process is performed. In some embodiments, the planarization process may, for example, comprise a chemical mechanical planarization (CMP) process or some other suitable process.

(74) As shown in cross-sectional view **1500** of FIG. **15**, a second dielectric layer **118** is formed directly over the first dielectric layer **114** and directly over the top electrode **116**. In some embodiments, the second dielectric layer **118** may, for example, be formed by depositing silicon dioxide, silicon nitride, silicon carbide, silicon oxycarbide, silicon oxynitride, or some other suitable material by a CVD process, a PVD process, an ALD process, or some other suitable process.

(75) As shown in cross-sectional view **1600** of FIG. **16**, a second masking layer **1602** is formed over the second dielectric layer **118**. The second dielectric layer **118** is then etched according to the second masking layer **1602** to form a second opening **1604** and a third opening **1606** in the second dielectric layer **118**. In some embodiments, the second opening **1604** and the third opening **1606** are directly over the top electrode **116** and uncover an upper surface of the top electrode **116**. In some embodiments, the second opening **1604** is a trench opening and the third opening **1606** is a via opening. In some embodiments, the second opening **1604** is formed by a first etching process while the third opening **1606** is formed by a second etching process, or vice versa.

(76) In some embodiments, the second masking layer **1602** may, for example, be or comprise a photoresist mask, a hard mask, or the like. In some embodiments, the etching may, for example, comprise a dry etching process or some other suitable process. In some embodiments, the second masking layer **1602** is removed after the etching.

(77) As shown in cross-sectional view **1700** of FIG. **17**, a third conductive layer **1702** is formed over the second dielectric layer **118**, directly over the top electrode **116**, in the second opening **1604**, and in the third opening **1606** to form a conductive via **120** in the third opening **1606** and directly over the top electrode **116**, and to form a first conductive line **122** in the second opening **1604** and directly over the conductive via **120**. In some embodiments, the third conductive layer **1702** may, for example, be formed by depositing titanium nitride, tantalum nitride, tungsten, copper, or some other suitable material by a sputtering process, an electrochemical deposition process, an electroless deposition process, or some other suitable process.

(78) As shown in cross-sectional view **1800** of FIG. **18**, a planarization process is performed on the third conductive layer **1702** to remove the third conductive layer **1702** from over the second dielectric layer **118** and to further define the first conductive line **122**. In some embodiments, the planarization process is also performed on the second dielectric layer **118**. In some embodiments,

an uppermost surface of the first conductive line **122** and uppermost surfaces of the second dielectric layer **118** are coplanar after the planarization process is performed. In some embodiments, the planarization process may, for example, comprise a CMP process or some other suitable process.

(79) As shown in cross-sectional view **1900** of FIG. **19**, a third masking layer **1902** is formed over the second dielectric layer **118** and over the first conductive line **122**. The second dielectric layer **118** is then etched according to the third masking layer **1902** to form a fourth opening **1904** in the second dielectric layer **118**. In some embodiments, the fourth opening **1904** is adjacent to the first conductive line **122** and uncovers a sidewall of the first conductive line **122**.

(80) In some embodiments, the third masking layer **1902** may, for example, be or comprise a photoresist mask, a hard mask, or the like. In some embodiments, the etching may, for example, comprise a dry etching process or some other suitable process. In some embodiments, the third masking layer **1902** is removed after the etching.

(81) As shown in cross-sectional view **2000** of FIG. **20**, a fourth conductive layer **2002** is formed over the second dielectric layer **118**, over the first conductive line **122**, and in the fourth opening **1904** to form a source line **124** in the fourth opening **1904** and on the sidewall of the first conductive line **122**. In some embodiments, the fourth conductive layer **2002** may, for example, be formed by depositing titanium nitride, tantalum nitride, tungsten, copper, or some other suitable material by a sputtering process, an electrochemical deposition process, an electroless deposition process, or some other suitable process.

(82) As shown in cross-sectional view **2100** of FIG. **21**, a planarization process is performed on the fourth conductive layer **2002** to remove the fourth conductive layer **2002** from over the second dielectric layer **118** and from over the first conductive line **122**. In addition, the planarization process further defines the source line **124**. In some embodiments, the planarization process is also performed on the second dielectric layer **118** and/or the first conductive line **122**. In some embodiments, an uppermost surface of the source line **124**, an uppermost surface of the first conductive line **122**, and one or more uppermost surfaces of the second dielectric layer **118** are coplanar after the planarization process is performed. In some embodiments, the planarization process may, for example, comprise a CMP process or some other suitable process.

(83) FIG. **22** illustrates a flow diagram of some embodiments of a method **2200** for forming a memory device comprising a top electrode over a memory element and a source line coupled to the top electrode. While method **2200** is illustrated and described below as a series of acts or events, it will be appreciated that the illustrated ordering of such acts or events are not to be interpreted in a limiting sense. For example, some acts may occur in different orders and/or concurrently with other acts or events apart from those illustrated and/or described herein. In addition, not all illustrated acts may be required to implement one or more aspects or embodiments of the description herein. Further, one or more of the acts depicted herein may be carried out in one or more separate acts and/or phases.

(84) At **2202**, one or more data storage layers are deposited over a first conductive layer. FIG. **9** illustrates a cross-sectional view **900** of some embodiments corresponding to act **2202**.

(85) At **2204**, the one or more data storage layers and the first conductive layer are patterned to form a memory element over a bottom electrode. FIG. **10** illustrates a cross-sectional view **1000** of some embodiments corresponding to act **2204**.

(86) At **2206**, a first dielectric layer is deposited over the memory element. FIG. **11** illustrates a cross-sectional view **1100** of some embodiments corresponding to act **2206**.

(87) At **2208**, the first dielectric layer is patterned to form first opening in the first dielectric layer and directly over the memory element, wherein a width of the first opening is less than a width of the memory element. FIG. **12** illustrates a cross-sectional view **1200** of some embodiments corresponding to act **2208**.

(88) At **2210**, a second conductive layer is deposited in the first opening to form a top electrode

directly over the memory element. FIG. 13 illustrates a cross-sectional view **1300** of some embodiments corresponding to act **2210**.

(89) At **2212**, a second dielectric layer is deposited directly over the first dielectric layer and directly over the top electrode. FIG. 15 illustrates a cross-sectional view **1500** of some embodiments corresponding to act **2212**.

(90) At **2214**, the second dielectric layer is patterned to form a second opening and a third opening in the second dielectric layer and directly over the top electrode. FIG. 16 illustrates a cross-sectional view **1600** of some embodiments corresponding to act **2214**.

(91) At **2216**, a third conductive layer is deposited in the third opening to form a conductive via directly over the top electrode, and the third conductive layer is deposited in the second opening to form a first conductive line directly over the conductive via. FIG. 17 illustrates a cross-sectional view **1700** of some embodiments corresponding to act **2216**.

(92) At **2218**, the second dielectric layer is patterned to form a fourth opening in the second dielectric layer and adjacent to the first conductive line. FIG. 19 illustrates a cross-sectional view **1900** of some embodiments corresponding to act **2218**.

(93) At **2220**, a fourth conductive layer is deposited in the fourth opening to form a source line in the fourth opening and abutting the first conductive line. FIG. 20 illustrates a cross-sectional view **2000** of some embodiments corresponding to act **2220**.

(94) Thus, the present disclosure relates to a memory device comprising a breakable top electrode over a memory element and a source line coupled to the top electrode for improving a performance of the memory device.

(95) Accordingly, in some embodiments, the present disclosure relates to an integrated chip comprising a bottom electrode arranged within a dielectric layer. A memory element is directly over the bottom electrode and is arranged within the dielectric layer. A top electrode is directly over the memory element and is arranged within the dielectric layer. A conductive via is directly over the top electrode. A pair of lines that extend along opposing sidewalls of the top electrode are directly over, and intersect, an uppermost surface of the memory element. The pair of lines are directly under, and intersect, a lowermost surface of the via.

(96) In other embodiments, the present disclosure relates to an integrated chip comprising a bottom electrode arranged within a dielectric layer. A memory element is directly over the bottom electrode and is arranged within the dielectric layer. A top electrode is directly over the memory element and is arranged within the dielectric layer. A first perimeter of a lowermost surface of the top electrode is arranged within a second perimeter of an uppermost surface of the memory element. A conductive via is directly over the top electrode. A first conductive line is directly over the conductive via and extends along a first direction. The first conductive line is disposed at a first height. A second conductive line is adjacent to the first conductive line. The second conductive line extends along a second direction transverse to the first direction. The second conductive line is arranged on a sidewall of the first conductive line.

(97) In yet other embodiments, the present disclosure relates to a method for forming an integrated chip. The method comprises forming a memory element over a bottom electrode. A first dielectric layer is deposited over the memory element. The first dielectric layer is patterned to form a first opening in the first dielectric layer and directly over the memory element. A distance between sidewalls of the first dielectric layer that define the first opening is less than a width of the memory element. A first conductive material is deposited in the first opening to form a top electrode in the first opening and directly over the memory element. A second dielectric layer is deposited over the top electrode and over the first dielectric layer. The second dielectric layer is patterned to form a second opening in the second dielectric layer and directly over the top electrode. A second conductive material is deposited in the second opening to form a first conductive line that extends in a first direction and that is directly over the top electrode. The second dielectric layer is patterned to form a third opening in the second dielectric layer and adjacent to the first conductive line. A

third conductive material is deposited in the third opening to form a source line on a sidewall of the first conductive line and extending in a second direction transverse to the first direction. The source line is electrically coupled to the top electrode.

(98) The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

## Claims

1. An integrated chip comprising: a bottom electrode arranged within a dielectric layer; a memory element directly over the bottom electrode and arranged within the dielectric layer; a top electrode directly over the memory element and arranged within the dielectric layer; and a conductive via directly over the top electrode, wherein a pair of lines that extend along opposing sidewalls of the top electrode are over, and intersect, an uppermost surface of the memory element, and wherein the pair of lines are under, and intersect, a lowermost surface of the conductive via.
2. The integrated chip of claim 1, further comprising: a first conductive line over the conductive via and elongated along a first direction; and a source line adjacent to the first conductive line and elongated along a second direction transverse to the first direction.
3. The integrated chip of claim 2, wherein the source line is electrically coupled to the top electrode through the first conductive line and the conductive via, wherein the source line is configured to provide a breakdown signal at the top electrode, the breakdown signal having a voltage that is higher than a voltage of a read signal and higher than a voltage of a write signal, and that is high enough to cause the top electrode to experience electromigration which creates an open circuit at the top electrode.
4. The integrated chip of claim 1, wherein a void exists along the top electrode and the void establishes an open circuit between the bottom electrode and the conductive via.
5. The integrated chip of claim 1, further comprising: a hard mask directly over the memory element, wherein the pair of lines intersect an uppermost surface of the hard mask.
6. The integrated chip of claim 5, wherein the hard mask vertically separates a lowermost surface of the top electrode from the uppermost surface of the memory element, and wherein the lowermost surface of the top electrode is on the uppermost surface of the hard mask.
7. The integrated chip of claim 5, wherein the hard mask vertically separates a lowermost surface of the top electrode from the uppermost surface of the memory element, and wherein the lowermost surface of the top electrode is below the uppermost surface of the hard mask.
8. The integrated chip of claim 5, wherein the top electrode extends through the hard mask to the uppermost surface of the memory element.
9. The integrated chip of claim 1, wherein the top electrode is on the uppermost surface of the memory element and the dielectric layer is on the uppermost surface of the memory element.
10. The integrated chip of claim 1, wherein the opposing sidewalls of the top electrode extend from the lowermost surface of the conductive via to the uppermost surface of the memory element.
11. An integrated chip comprising: a bottom electrode arranged within a dielectric layer; a memory element over the bottom electrode and arranged within the dielectric layer; a top electrode over the memory element and arranged within the dielectric layer, wherein a width between outermost sidewalls of the top electrode less than a width between outermost sidewalls of the memory element; a conductive via over the top electrode; a first conductive line over the conductive via and

- extending along a first direction; and a second conductive line adjacent to the first conductive line and extending along a second direction transverse to the first direction, wherein a sidewall of the second conductive line is on a sidewall of the first conductive line.
12. The integrated chip of claim 11, wherein the second conductive line is configured to supply a voltage across the top electrode that is high enough to break the top electrode.
13. The integrated chip of claim 11, wherein the dielectric layer is directly over an uppermost surface of the memory element.
14. The integrated chip of claim 11, wherein a ratio of the width between the outermost sidewalls of the top electrode to the width between the outermost sidewalls of the memory element is less than 0.5.
15. The integrated chip of claim 11, wherein a lowermost surface of the top electrode is below an uppermost surface of the memory element.
16. The integrated chip of claim 11, further comprising: a conductive hard mask directly between the top electrode and the memory element.
17. An integrated chip comprising: a bottom electrode over a substrate; a memory element over the bottom electrode; a conductive hard mask over the memory element; a top electrode over the conductive hard mask; a conductive via over the top electrode; a first conductive line over the conductive via and extending along a first direction; and a second conductive line adjacent to the first conductive line, coupled to the top electrode by the first conductive line and the conductive via, and extending along a second direction transverse to the first direction, wherein a width of the top electrode is less than a width of the conductive hard mask.
18. The integrated chip of claim 17, wherein an upper portion of the top electrode is spaced over and electrically isolated from a lower portion of the top electrode such that the conductive via is electrically isolated from the memory element.
19. The integrated chip of claim 17, wherein the width of the conductive hard mask is approximately equal to a width of the memory element.
20. The integrated chip of claim 17, wherein the top electrode comprises a first conductive material and the conductive hard mask comprises a second conductive material different than the first conductive material.
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